

# RKP201KK

Silicon Epitaxial Trench Pin Diode for Antenna Switching

REJ03G1224-0200 Rev.2.00 Sep 06, 2005

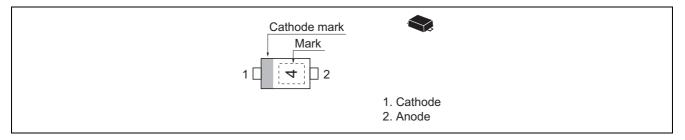
### Features

- Adopting the trench structure minimize terminal capacitance. (C = 0.35 pF max)
- Low forward resistance. ( $rf = 2.0 \Omega max$ )
- Low operation current.
- Super small Flat Lead Package (SFP) is suitable for surface mount design.

### **Ordering Information**

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
RKP201KK	4	SFP	PUSF0002ZB-A
			(SFP)

# **Pin Arrangement**





# **Absolute Maximum Ratings**

			(Ta = 25°C)	
Item	Symbol	Ratings	Unit	
Reverse voltage	V <sub>R</sub>	30	V	
Forward current	lF	100	mA	
Power dissipation	Pd	150	mW	
Junction temperature	Tj	125	°C	
Storage temperature	Tstg	-55 to +125	۵°	

### **Electrical Characteristics**

(Ta = 25°C)

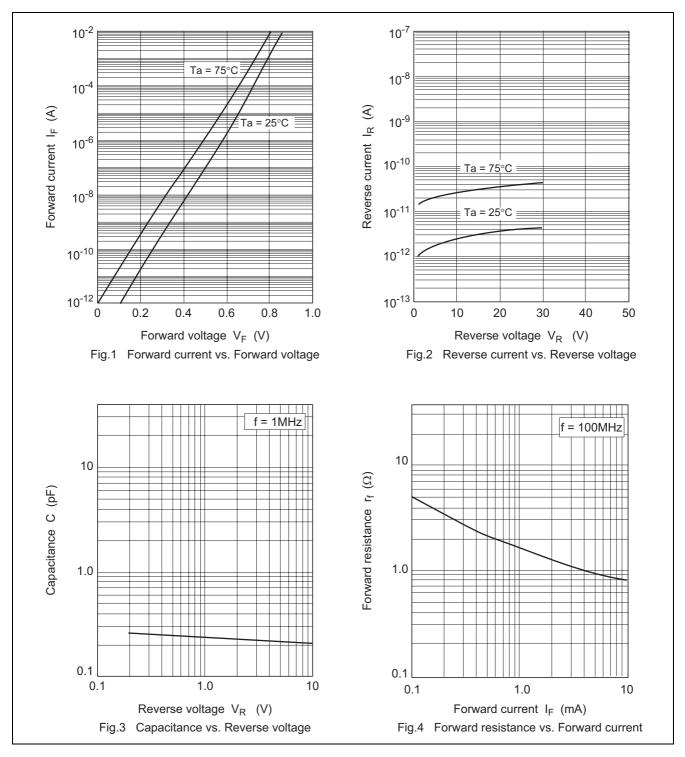
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I <sub>R</sub>	—	—	100	nA	V <sub>R</sub> = 30 V
Forward voltage	V <sub>F</sub>	—	—	0.9	V	$I_F = 2 \text{ mA}$
Capacitance	С	—	—	0.35	pF	$V_R = 1 V, f = 1 MHz$
Forward resistance	r <sub>f</sub>	_	_	2.0	Ω	I <sub>F</sub> = 2 mA, f = 100 MHz
ESD-Capability *1	—	100			V	C = 200 pF, R = 0 $\Omega$ , Both forward and reverse direction 1 pulse.

Notes: 1. Failure criterion ;  $I_R > 100 \ nA$  at  $V_R$  = 30 V

2. SFP package, the material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

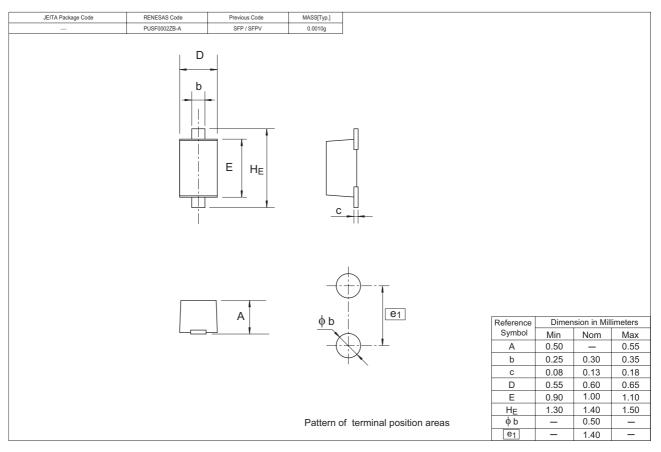


### **Main Characteristic**





## Package Dimensions





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